## **High Voltage Transistor**

### **PNP Silicon**

#### **Features**

- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	-150	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	-160	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	-500	mAdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C	P <sub>D</sub>	225	mW
Derate Above 25°C		1.8	mW/°C
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T <sub>A</sub> = 25°C	P <sub>D</sub>	300	mW
Derate Above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in 99.5% alumina.

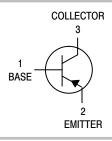


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SOT-23 (TO-236) CASE 318 STYLE 6



### MARKING DIAGRAM



2L = Specific Device Code

M = Date Code\*

■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT5401LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBT5401LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBT5401LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
NSVMMBT5401LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	-150	-	Vdc
Collector – Base Breakdown Voltage ( $I_C = -100 \mu Adc$ , $I_E = 0$ )	V <sub>(BR)CBO</sub>	-160	_	Vdc
Emitter – Base Breakdown Voltage ( $I_E = -10 \mu Adc$ , $I_C = 0$ )	V <sub>(BR)EBO</sub>	-5.0	_	Vdc
Collector–Base Cutoff Current $(V_{CB} = -120 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -120 \text{ Vdc}, I_E = 0, T_A = 100^{\circ}\text{C})$	Ісво		–50 –50	nAdc μAdc
ON CHARACTERISTICS				
DC Current Gain $ \begin{aligned} &(I_C = -1.0 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}) \\ &(I_C = -10 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}) \\ &(I_C = -50 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}) \end{aligned} $	h <sub>FE</sub>	50 60 50	_ 240 _	-
Collector – Emitter Saturation Voltage ( $I_C = -10$ mAdc, $I_B = -1.0$ mAdc) ( $I_C = -50$ mAdc, $I_B = -5.0$ mAdc)	V <sub>CE(sat)</sub>	- -	-0.2 -0.5	Vdc
Base – Emitter Saturation Voltage ( $I_C = -10$ mAdc, $I_B = -1.0$ mAdc) ( $I_C = -50$ mAdc, $I_B = -5.0$ mAdc)	V <sub>BE(sat)</sub>	- -	-1.0 -1.0	Vdc
SMALL-SIGNAL CHARACTERISTICS				
Current – Gain — Bandwidth Product (I <sub>C</sub> = –10 mAdc, V <sub>CE</sub> = –10 Vdc, f = 100 MHz)	f <sub>T</sub>	100	300	MHz
Output Capacitance ( $V_{CB} = -10 \text{ Vdc}$ , $I_E = 0$ , $f = 1.0 \text{ MHz}$ )	C <sub>obo</sub>	-	6.0	pF
Small Signal Current Gain (I <sub>C</sub> = -1.0 mAdc, V <sub>CE</sub> = -10 Vdc, f = 1.0 kHz)	h <sub>fe</sub>	40	200	_
Noise Figure $(I_C = -200 \ \mu \text{Adc}, \ V_{CE} = -5.0 \ \text{Vdc}, \ R_S = 10 \ \Omega, \ f = 1.0 \ \text{kHz})$	NF	_	8.0	dB

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

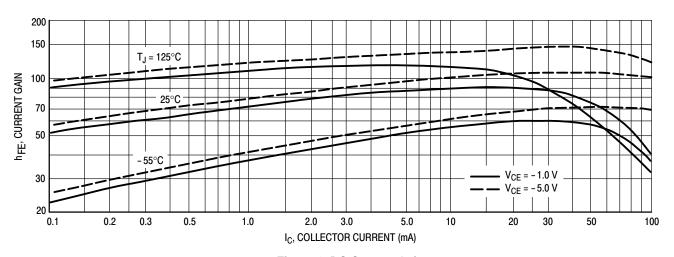


Figure 1. DC Current Gain

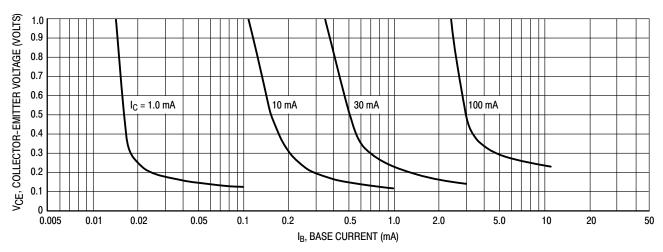


Figure 2. Collector Saturation Region

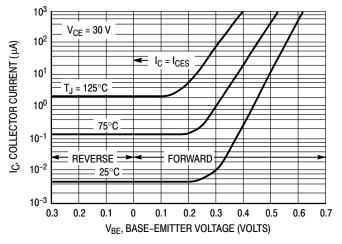


Figure 3. Collector Cut-Off Region

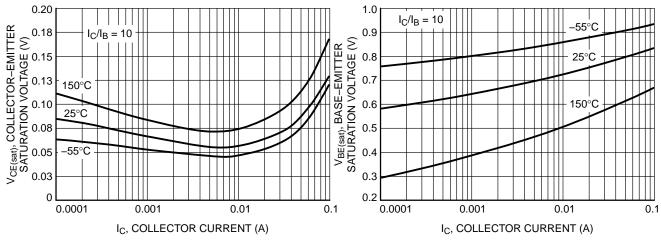


Figure 4. Collector Emitter Saturation Voltage vs. Collector Current

Figure 5. Base Emitter Saturation Voltage vs. Collector Current

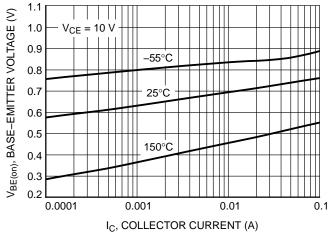
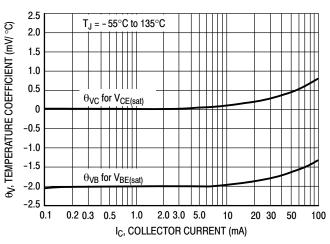


Figure 6. Base Emitter Voltage vs. Collector Current



**Figure 7. Temperature Coefficients** 

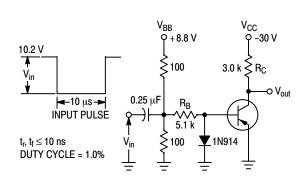


Figure 8. Switching Time Test Circuit

Values Shown are for I<sub>C</sub> @ 10 mA

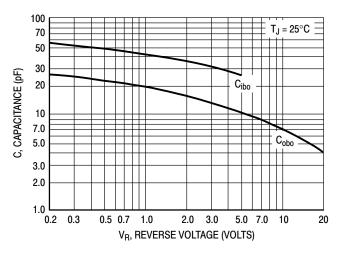
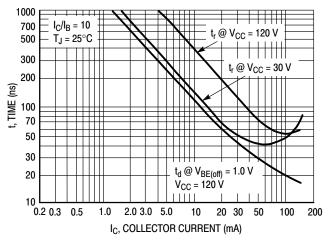


Figure 9. Capacitances



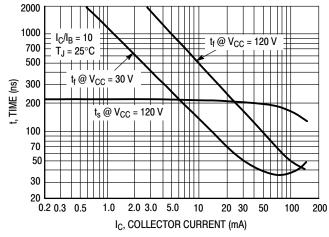
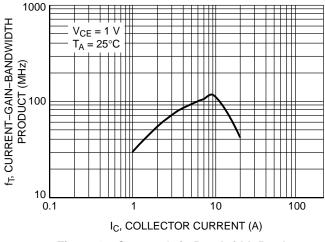


Figure 10. Turn-On Time

Figure 11. Turn-Off Time



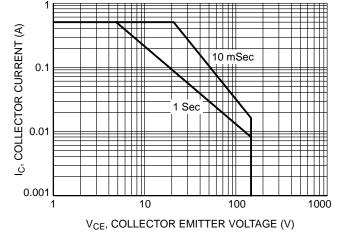
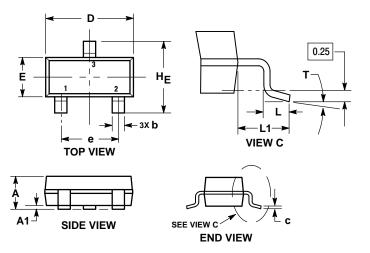


Figure 12. Current Gain Bandwidth Product

Figure 13. Safe Operating Area

### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR** 



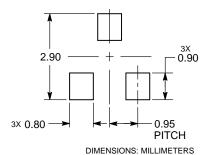
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

#### STYLE 6:

- PIN 1. BASE
  - **EMITTER**
  - COLLECTOR

### **RECOMMENDED** SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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